

Component Side

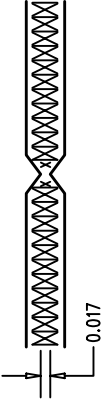
SIZE	QTY	SYM	PLTD
15	13	W	PLTD
35	6	X	PLTD
72	2	Y	NPLTD
95	10	Z	PLTD

REVISIONS		
REV	DESCRIPTION	DATE


- ART01 = LAYER 1 (COMPONENT SIDE)
- ART02 = LAYER 2 (GND)
- ART03 = LAYER 3 (SIGNAL)
- ART04 = LAYER 4 (SOLDER SIDE)

NOTES : Unless Otherwise Specified

- MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS
- FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC)
- SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT
- SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
- ALL DIMENSIONS ARE IN INCHES
- SCORING:



Fabrication Drawing

<div>APPROVALS</div> <table><tr><td></td><td>INIT</td><td>DATE</td></tr><tr><td>DRAWN</td><td></td><td></td></tr><tr><td>CHECK</td><td></td><td></td></tr><tr><td>DESIGN</td><td></td><td></td></tr><tr><td>ENGR</td><td></td><td></td></tr><tr><td></td><td></td><td></td></tr></table>			INIT	DATE	DRAWN			CHECK			DESIGN			ENGR						<div>1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900</div>		<div>TITLE: 1.3MHz Boost and SEPIC DC/DC Converter in SC70</div>	
			INIT	DATE																			
		DRAWN																					
		CHECK																					
		DESIGN																					
		ENGR																					
SIZE		A	DEMO BRD	DC545	LT3460SC6	REV.	A																
DES-						SHT 1 of 1																	
SCALE = NONE																							